

L Number	Hits	Search Text	DB	Time stamp
-	21	"non-key" and semiconductor	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/04/27 11:33
-	12	5,978,807	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/04/27 14:36
-	2	"common tool set capacity"	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/04/27 14:36
-	1	"common tool set" and semiconductor	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/04/27 14:37
-	605	capacity and overall and wafer and semiconductor and calculating	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/04/27 14:37
-	5	(capacity and overall and wafer and semiconductor and calculating) and "overall capacity" and dividing	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/04/27 14:50
-	2	"capacity consumption factor"	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/04/27 14:51
-	15	"5946212"	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/04/27 14:53
-	1		USPAT	2004/04/27 14:51
-	1		USPAT	2004/04/27 14:51
-	1		USPAT	2004/04/27 14:52
-	20	"capacity planning" and technologies and "tool sets"	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/04/27 15:21
-	26	"technology based" and "design based" and semiconductor	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/04/27 15:30
-	632	fabricator and technology and design	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/04/27 15:30
-	11	(fabricator and technology and design) and organizing	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/04/27 15:31
-	210	(fabricator and technology and design) and wafer	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/04/27 15:31